IPC ASSOCIATION ELECTRONIC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the relevel parts, the declaration encompasses all lower level mate				within the manufacturer level materials for w	er listed ite hich the ma	m. Note: nufactur	: if the item is an as eer has engineering	sembly with loweresponsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Typ Distribute								ials and Mfg Information					
Supplie	r Information													
Company name*			Company unique ID			ı	Unique ID Authority				Response Date*			
)n Semic	onductor										2021-02-04			
Contact N	lame	Title - Contact			]	Phone - Contact*				Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*		Title - Representative			]	Phone - Representative*				Email - Representative*			
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Ite		n Number Mfr Item Name				Effective Da	Date Version Manufacturing Site		V	eight*	UOM	Unit Type	
		SS36		3A 100V SCHOTTKY RECT			2021-02-04		1	PANJITFG		32.5	mg	Each
<b>Aanufa</b>	cturing Process Inform	ation							·					·
	Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-	J-STD-020 MSL Rating Peal			eak Process Body Temperature   Max Time at Peak			Temperatu	re Nun	nber of Reflow Cyc	les
Matte Tin (Sn) - annealed CU Alloy 1					260		C	30	second	s <b>3</b>				
Comments	S													
vel 1 - m	naximum time at peak tempera	ture during sol	dering is 10-3	0 seconds										
or more	information regarding materia	al composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.798	mg	Supplier	Silicon (Si)	7440-21-3		3.768	mg
			В	Nickel (Ni)	7440-02-0		0.0057	mg
			Supplier	Gold (Au)	7440-57-5		0.0209	mg
			В	Arsenic (As)	7440-38-2		0.0034	mg
Die Attach Solder	4.36	mg	Supplier	Silver (Ag)	7440-22-4		0.109	mg
			A	Lead (Pb)	7439-92-1	7a	4.033	mg
			Supplier	Tin (Sn)	7440-31-5		0.218	mg
Lead Frame	90.9231	mg	Supplier	Iron (Fe)	7439-89-6		0.1091	mg
			Supplier	Copper (Cu)	7440-50-8		90.7867	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0273	mg
Mold Compound-Black	132.0	mg		Metal Hydroxide	proprietary data		4.62	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		10.56	mg
			Supplier	Carbon Black (C)	1333-86-4		0.66	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		105.6	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		10.56	mg
Plating	1.4189	mg	Supplier	Tin (Sn)	7440-31-5		1.4189	mg